TRADEMARK ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	SECURITY INTEREST

CONVEYING PARTY DATA

Name	Formerly	Execution Date	Entity Type
Akrion Technologies, Inc.		08/12/2008	CORPORATION:

RECEIVING PARTY DATA

Name:	Sunrise Capital Partners, L.P.
Street Address:	245 Park Avenue
City:	New York
State/Country:	NEW YORK
Postal Code:	10167
Entity Type:	LIMITED PARTNERSHIP:

PROPERTY NUMBERS Total: 6

Property Type	Number	Word Mark
Registration Number:	2691082	AKRION
Registration Number:	2295797	GOLDFINGER
Registration Number:	2993100	LUCID2
Registration Number:	1598327	SUBMICRON
Registration Number:	1574491	SUNBURST
Registration Number:	2040148	VERTEQ

CH $165.00 2691082

CORRESPONDENCE DATA

Fax Number: (215)665-8760
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: 2156653866
Email: suzanne.chocklette@bipc.com
Correspondent Name: Brian L. Belles
Address Line 1: 1835 Market Street, 14th Floor
Address Line 4: Philadelphia, PENNSYLVANIA 19103

ATTORNEY DOCKET NUMBER:	0075053-000002

NAME OF SUBMITTER:	Brian L. Belles
Signature:	/Brian L. Belles/
Date:	09/01/2008

Total Attachments: 13
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INTELLECTUAL PROPERTY SECURITY AGREEMENT

This Intellectual Property Security Agreement ("Agreement") dated August 12, 2008 is entered into between Akrion, Technologies, Inc. ("Grantor") and Sunrise Capital Partners, L.P. (hereinafter "Sunrise Capital").

RECITALS:

A. In March 2004, Akrion, Inc. and/or Goldfinger Technologies, LLC issued a secured promissory note to Sunrise Capital in connection with Akrion, Inc.'s and/or Goldfinger Technologies, LLC's acquisition of the assets of Verteq, Inc, which included certain items of the Intellectual Property (defined below).

B. In September 2004, Akrion, Inc. and/or Goldfinger Technologies, LLC issued a secured promissory note to Sunrise Capital for working capital, to repay all amounts owing to Sunrise Capital under a short-term borrowing arrangement, to reimburse Sunrise Capital for certain expenses incurred on our behalf, to pay all accrued fees owing under a management agreement with the general partner of Sunrise Capital and to pay a fee to terminate the management agreement and another agreement with Sunrise Capital's general partner under which Akrion, Inc. and/or Goldfinger Technologies, LLC agreed to pay the general partner specified amounts in connection with certain change in control transactions.

C. In January 2005, Akrion, Inc. and/or Goldfinger Technologies, LLC issued a secured promissory note to Sunrise Capital for working capital purposes.

D. In May 2005, Akrion, Inc. and/or Goldfinger Technologies, LLC issued an unsecured promissory note to Sunrise Capital, which was later amended to be secured by a lien on substantially all of Akrion, Inc.'s and/or Goldfinger Technologies, LLC's assets for working capital purposes.

E. In April 2006, Akrion, Inc. and/or Goldfinger Technologies, LLC issued a secured promissory note to Sunrise Capital for working capital purposes.

F. In the promissory notes noted in Sections A-E above (collectively the "Promissory Notes") and/or documents related to the Promissory Notes, Akrion, Inc. and/or Goldfinger Technologies, LLC granted a security interest in the Intellectual Property to Sunrise Capital.

G. In an Assignment Agreement dated January 25, 2006, Goldfinger Technologies, LLC assigned all of its right, title, and interest in and associated with the Intellectual Property to Akrion Technologies, Inc. according to the terms set forth therein.

H. In an Assignment Agreement dated January 25, 2006, Goldfinger Technologies, LLC assigned all of its right, title, and interest in, to and associated with the Intellectual Property to Akrion Technologies, Inc., according to the terms set forth therein.

I. In an Assignment Agreement dated January 25, 2006, Akrion, Inc. assigned all of its right, title, and interest in, to and associated with the Intellectual Property to Akrion Technologies, Inc., according to the terms set forth therein.

NOW THEREFORE, in consideration of the mutual promises, covenants, conditions, representations, and warranties hereinafter set forth and for other good and valuable consideration, and intending to be legally bound, the parties hereto mutually agree as follows:

1. INTELLECTUAL PROPERTY DEFINED

The term "Intellectual Property," as used in this Agreement, means:

(i) Each of the patents and patent applications which are presently owned by, or under an obligation of assignment to, Grantor (including all of Grantor's right, title, and interest, in and to the patents and patent applications listed on Exhibit A, attached hereto, as the same may be updated hereafter from time to time), in whole or in part, and all patent rights with respect thereto throughout the world, including all proceeds thereof (including license royalties and proceeds of infringement suits), foreign filing rights, and rights to extend such patents and patent rights;

(ii) All of Grantor's right, title, and interest in all present and/or future inventions, whether patentable or not, and to file applications for patent under federal patent law or regulation of any foreign country, and to request reexamination and/or reissue of the patents, the right (without obligation) to sue or bring interference proceedings in the name of Grantor or in the name of Sunrise Capital for past, present, and future infringements of the patents, and all rights (but not obligations) corresponding thereto in the United States and any foreign country;

(iii) Each of the trademarks and rights and interest which are capable of being protected as trademarks (including all of Grantor's right to the trademark registrations listed on Exhibit B, attached hereto, as the same may be updated hereafter from time to time and all other trademarks, service marks, designs, logos, indicia, tradenames, corporate names, company names, business names, fictitious business names, trade styles, and other source or business identifiers, and applications pertaining thereto), which are presently owned by, or under an obligation of assignment to, Grantor, in whole or in part, and all trademark rights with respect thereto throughout the world, including all goodwill associated therewith and all proceeds thereof (including license royalties and proceeds of infringement suits), and rights to renew and extend such trademarks and trademark rights;

(iv) All of Grantor's right, title and interest to register trademark claims under any state or federal trademark law or regulation of any foreign country and to apply for, renew, and extend the trademark registrations and trademark rights, the right (without obligation) to sue or bring opposition or cancellation proceedings in the name of Grantor or in the name of Sunrise Capital for past, present, and future infringements of the trademarks, registrations, or trademark rights and all rights (but not obligations) corresponding thereto in the United States and any foreign country;

(v) All general intangibles relating to the foregoing; and

(vi) All proceeds of any and all of the foregoing (including, without limitations, license royalties and proceeds of infringement suits) and, to the extent not otherwise included, all payments under insurance, or any indemnity, warranty, or guaranty payable by reason of loss or damage to or otherwise with respect to the Intellectual Property.

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Notwithstanding the foregoing, "Intellectual Property" shall not include any license, property or contract right the granting of a security interest in which would be prohibited by law or contract.

2. GRANT OF SECURITY INTEREST.

Grantor hereby grants Sunrise Capital, a security interest in all of Grantor's right, title, and interest in and to the Intellectual Property to secure the obligations set forth in the Promissory Notes.

This security interest is granted in conjunction with the security interest granted under the Promissory Notes and any and all documents related to the Promissory Notes. Sunrise Capital's rights and remedies in the security interest are in addition to those in the Promissory Notes and any and all documents related to the Promissory Notes, and those available in law or equity.

To the extent possible and/or allowed by law, the security interest to the Intellectual Property granted to Sunrise Capital in this agreement are intended to be *nunc pro tunc* as of the date afforded by the Promissory Notes.

Sunrise Capital's rights, powers and interests are cumulative with every right, power or remedy provided hereunder. Sunrise Capital's exercise of its rights, powers or remedies in this Agreement, the Promissory Notes or any other document does not preclude the simultaneous or later exercise of any or all other rights, powers or remedies.

3. GENERAL PROVISIONS.

Except as stated herein, all other terms, warranties, conditions, representations, obligations, and/or provisions relating to Sunrise Capital's security interest in the Intellectual Property is dictated by the relevant terms, warranties, conditions, representations, obligations, and/or provisions set forth in the Promissory Notes and documents related to the Promissory Notes.

IN WITNESS WHEREOF, the parties have executed this Agreement on the date first written above.

GRANTOR:

AKRION TECHNOLOGIES, INC.

By:____________________
Title: President / CEO

SUNRISE CAPITAL:

SUNRISE CAPITAL PARTNERS, L.P.

By:____________________
Title:____________________

Exhibit A
"Patents and Patent Applications"

COUNTRY	SERIAL NO	FILED	PATENT NO	ISSUE DATE	TITLE
US	10/111,332	4 /18/2002	6,817,369	11/16/2004	APPARATUS AND METHOD FOR THE CLEANING OF SUBSTRATES
US	10/760,596	1 /20/2004	6,892,738	5 /17/2005	Apparatus and Methods for Reducing Damage to Substrates During Megasonic Cleaning Process
US	10/098,847	3 /15/2002	6,722,056	4 /20/2004	Apparatus and Methods for Vapor Generation System
US	09/171,757	10/23/1998	6,145,520	11/14/2000	Apparatus for Processing Substrates in a Fluid Tank
US	10/031,923	4 /17/2002	6,799,588	10/5 /2004	Apparatus for Treating Substrates
US	10/358,636	2 /5 /2003	6,907,890	6 /21/2005	Capillary Drying of Substrates
US	90/002,139	9 /14/1990	B1 4,571,850	1 /21/1992	Centrifugal Wafer Processor
US	09/103,930	6 /24/1998	6,122,837	9 /26/2000	Centrifugal Wafer Processor and Method
US	10/117,725	4 /5 /2002	6,766,818	7 /27/2004	Chemical Concentration Control Device
US	09/227,226	1 /8 /1999	6,170,703	1 /9 /2001	Chemical Dispensing System And Method
US	08/356,048	12/14/1994	5,437,710	8 /1 /1995	Chemical Processing System for Maintaining Concentration of Semiconductor Processing Solution
US	07/043,852	4/29/1987	4,804,007	2/14/1989	Cleaning Apparatus
US	10/091,011	3 /4 /2002	6,837,944	1 /4 /2005	Cleaning and Drying Method and Apparatus
US	08/920,347	8 /27/1997	6,041,938	3 /28/2000	Compliant Process Cassette
US	08/825,883	4 /2 /1997	6,286,688	9 /11/2001	Compliant Silicon Wafer Handling System
US	09/869,213	9 /22/2001	6,805,754	10/19/2004	Device and Method for Processing Substrates
US	09/367,683	12/3 /1999	6,647,641	11/18/2003	Device and Method for the Treatment of Substrates in a Fluid Container
US	08/862,890	5 /23/1997	5,954,068	9 /21/1999	Device and Method for Treating Substrates in a Fluid Container
US	08/875,408	7 /3 /1997	5,902,402	5 /11/1999	Device for Chemical Wet Treatment
US	08/761,717	12/6 /1996	6,240,938	6 /5 /2001	Device for Treating Substrates in a Fluid Container
US	09/171,271	6 /22/1999	6,269,822	8 /7 /2001	Device for Wet-Treatment of Substrates
US	10/085,565	2 /26/2002	6,843,859	1 /18/2005	Dump Door
US	09/395,398	9 /14/1999	6,165,912	12/26/2000	Electroless Metal Deposition of Electronic Components in an Enclosable Vessel
US	09/068,618	7 /7 /1998	6,523,552	2 /25/2003	Facility for Treating Objects in a Process Tank
US	09/040,176	3 /17/1998	6,125,551	10/3 /2000	Gas Seal and Support for Rotating Semiconductor Processor
US	08/851,668	5 /6 /1997	5,807,408	9 /15/1998	Industrial Robot Safety Device That Shuts Down Operation in Response to Variation in Tension of a Rope
US	10/053,449	1 /17/2002	6,871,657	3 /29/2005	Low Profile Wafer Carrier
US	10/171,426	6 /12/2002	6,754,980	6 /29/2004	Megasonic Cleaner and Dryer
US	10/864,927	6 /10/2004	7,100,304	9 /5 /2006	Megasonic Cleaner and Dryer
BE	02742054.6	6 /12/2002	1402566	2 /14/2007	Megasonic Cleaner and Dryer System

COUNTRY	SERIAL NO	FILED	PATENT NO	ISSUE DATE	TITLE
DE	02742054.6	6 /12/2002	1402566	2 /14/2007	Megasonic Cleaner and Dryer System
EP	02742054.6	6 /12/2002	1402566	2 /14/2007	Megasonic Cleaner and Dryer System
FR	02742054.6	6 /12/2002	1402566	2 /14/2007	Megasonic Cleaner and Dryer System
JP	2003-516068	6 /12/2002	4114188	4 /25/2008	Megasonic Cleaner and Dryer System
US	10/171,430	6 /12/2002	6,928,751	8 /16/2005	Megasonic Cleaner and Dryer System
US	09/906,384	7 /16/2001	6,684,890	2 /3 /2004	Megasonic Cleaner Probe System with Gasified Fluid
US	10/742,214	12/19/2003	7,047,989	5 /23/2006	Megasonic Cleaner Probe System with Gasified Fluid
US	10/864,929	6 /10/2004	7,156,111	1 /2 /2007	Megasonic Cleaner Probe System with Gasified Fluid
US	07/144,515	1/15/1988	4,869,278	9/26/1989	Megasonic Cleaning Apparatus
US	07/272,501	11/16/1988	4,998,549	3/12/1991	Megasonic Cleaning Apparatus
US	07/482,086	2/15/1990	5,037,481	8/6/1991	Megasonic Cleaning Apparatus
US	90/002,852	3/30/1993	4,869,278	5/11/1993	Megasonic Cleaning Apparatus
US	90/002,851	10/2/1992	4,998,549	5/11/1993	Megasonic Cleaning Apparatus
US	90/002,853	10/2/1992	5,037,481	5/11/1993	Megasonic Cleaning Apparatus
US	07/791,094	11/12/1991	5,247,954	9 /28/1993	Megasonic Cleaning System
US	08/316,940	10/3 /1994	5,534,076	7 /9 /1996	Megasonic Cleaning System
US	08/277,792	7 /20/1994	5,625,249	4 /29/1997	Megasonic Cleaning System
US	10/341,425	1 /10/2003	7,104,268	9 /12/2006	Megasonic Cleaning System with Buffered Cavitation Method
US	09/922,509	8 /3 /2001	6,679,272	1 /20/2004	Megasonic Probe Energy Attenuator
US	10/059,682	1 /29/2002	7,287,537	10/30/2007	Megasonic Probe Energy Director
US	08/042,889	4 /5 /1993	5,365,960	11/22/1994	Megasonic Transducer Assembly
US	10/117,768	4 /5 /2002	6,532,974	3 /18/2003	Megazone System
US	10/117,739	4 /5 /2002	6,842,998	1 /18/2005	Membrane Dryer
US	10/951,009	9 /27/2004	6,928,750	8 /16/2005	Membrane Dryer
US	08/275,807	7 /15/1994	5,556,479	9 /17/1996	Method and Apparatus for Drying Semiconductor Wafers
US	09/600,084	6 /30/2000	6,607,604	8 /19/2003	Method and Apparatus for Treating Substrates
US	09/918,750	7 /31/2001	6,730,177	5 /4 /2004	Method and Apparatus for Washing and/or Drying Using A Revolved Coanda Profile
US	08/367,358	1 /13/1995	5,569,330	10/29/1996	Method and Device for Chemically Treating Substrates
US	08/952,708	5 /2 /1996	5,879,464	3 /9 /1999	Method and Device for Wet-Processing Substrates In A Vessel
US	10/053,364	1 /18/2002	6,767,877	7 /27/2004	Method and System for Chemical Injection in Silicon Wafer Processing
US	09/257,488	2 /25/1999	6,261,845	7 /17/2001	Method and Systems for Determining Chemical Concentrations and Controlling the Processing of Semiconductor Substrates
US	09/478,094	1 /5 /2000	6,517,636	2 /11/2003	Method For Reducing Particle Contamination During The Wet Processing of Semiconductor Substances
US	10/634,440	8 /5 /2003	6,863,836	3 /8 /2005	Method for Removal of Photoresist Using Sparger

COUNTRY	SERIAL NO	FILED	PATENT NO	ISSUE DATE	TITLE
US	10/304,583	11/25/2002	6,626,189	9 /30/2003	Method of Processing Substrates Using Pressurized Mist Generation
US	09/235,091	1 /21/1999	6,153,533	11/28/2000	Method of Using A Compliant Process Cassette
US	09/096,898	6 /12/1998	5,972,123	10/26/1999	Methods for Treating Semiconductor Wafers
US	09/025,612	2 /18/1998	6,136,724	10/24/2000	Multiple Stage Wet Processing Chamber
US	10/117,778	4 /5 /2002	6,840,250	1 /11/2005	Nextgen Wet Process Tank
US	10/014,121	12/11/2001	6,732,749	5 /11/2004	Particle Barrier Drain
US	10/366,054	2 /13/2003	6,818,563	11/16/2004	Process and Apparatus for Removal of Photoresist from Semiconductor Wafers Using Spray Nozzles
US	09/263,344	3 /5 /1999	6,264,036	7 /24/2001	Process Cassette
US	07/876,043	4 /30/1992	5,234,540	8 /10/1993	Process for Etching Oxide Films in a Sealed Photochemical Reactor
US	10/909,764	8 /2 /2004	7,169,253	1 /30/2007	Process Sequence for Photoresist Stripping and Cleaning of Photomasks for Integrated Circuit Manufacturing
US	09/262,991	3 /5 /1999	6,245,250	6 /12/2001	Process Vessel
US	10/140,029	5 /6 /2002	7,185,661	3 /6 /2007	Reciprocating Megasonic Probe
US	08/361,139	12/21/1994	5,656,097	8 /12/1997	Semiconductor Wafer Cleaning System
US	08/908,330	8 /7 /1997	5,908,509	6 /1 /1999	Semiconductor Wafer Cleaning System
US	08/910,033	8 /11/1997	5,950,645	9 /14/1999	Semiconductor Wafer Cleaning System
US	08/908,345	8 /7 /1997	5,996,595	12/7 /1999	Semiconductor Wafer Cleaning System
US	09/358,568	7 /20/1999	6,158,445	12/20/2000	Semiconductor Wafer Cleaning System
US	09/694,938	10/23/2000	6,378,534	4 /30/2002	Semiconductor Wafer Cleaning System
US	07/598,909	10/16/1990	5,148,823	9 /22/1992	Single Chamber Megasonic Energy Cleaner
US	07/598,426	10/16/1990	5,090,432	2 /25/1992	Single Wafer Megasonic Semiconductor Wafer Processing System
US	07/809,799	12/18/1991	5,286,657	2 /15/1994	Single Wafer Megasonic Semiconductor Wafer Processing System
US	10/171,429	6 /12/2002	6,923,192	8 /2 /2005	Stackable Process Chambers
US	09/869,219	6 /22/2001	6,569,302	5 /27/2003	Substrate Carrier
US	10/699,042	10/31/2003	6,955,727	10/18/2005	Substrate Process Tank with Acoustical Source Transmission and Method of Processing Substrate
US	09/308,850	5 /24/1999	6,189,552	2 /20/2001	Substrate Processing Device
US	10/895,511	7 /20/2004	7,311,847	12/25/2007	System and Method for Point-of-Use Filtration and Purification of Fluids Used in Substrate Processing
US	10/052,823	1 /17/2002	6,649,018	11/18/2003	System for Removal of Photoresist Using Sparger
US	09/227,637	1 /8 /1999	6,328,809	12/11/2001	Vapor Drying System and Method
US	07/837,221	2 /18/1992	5,226,242	7 /13/1993	Vapor Jet Dryer Apparatus and Method
US	07/837,221	2 /18/1992	5,226,242	7 /13/1993	Vapor Jet Dryer Apparatus and Method
US	08/213,599	3 /16/1994	5,539,995	7 /30/1996	Vapor Processing System
US	10/243,463	9 /12/2002	6,681,782	1 /27/2004	Wafer Cleaning
US	10/243,486	9 /12/2002	6,684,891	2 /3 /2004	Wafer Cleaning
US	10/726,774	12/3 /2003	7,117,876	10/10/2006	Wafer Cleaning

COUNTRY	SERIAL NO	FILED	PATENT NO	ISSUE DATE	TITLE
US	11/386,634	3 /22/2006	7,211,932	5 /1 /2007	Wafer Cleaning
US	11/375,907	3 /15/2006	7,268,469	9 /11/2007	Wafer Cleaning
KR	99-7002749	7 /8 /1997	0392242	7 /9 /2003	Wafer Cleaning System
KR	10-2002-7011609	7 /8 /1997	0392243	7 /9 /2003	Wafer Cleaning System
BE	97933309.3	7 /8 /1997	0938745	3 /20/2002	Wafer Cleaning System
DE	97933309.3	7 /8 /1997	0938745	3 /20/2002	Wafer Cleaning System
EP	97933309.3	7 /8 /1997	0938745	3 /20/2002	Wafer Cleaning System
FR	97933309.3	7 /8 /1997	0938745	3 /20/2002	Wafer Cleaning System
GB	97933309.3	7 /8 /1997	0938745	3 /20/2002	Wafer Cleaning System
IT	97933309.3	7 /8 /1997	0938745	3 /20/2002	Wafer Cleaning System
NL	97933309.3	7 /8 /1997	0938745	3 /20/2002	Wafer Cleaning System
JP	516502/98	7 /8 /1997	3493492	11/21/2003	Wafer Cleaning System
US	08/724,518	9 /30/1996	6,039,059	3 /21/2000	Wafer Cleaning System
US	09/057,182	4 /8 /1998	6,140,744	10/31/2000	Wafer Cleaning System
US	09/643,328	8 /22/2000	6,295,999	10/2 /2001	Wafer Cleaning System
US	09/953,504	9 /13/2001	6,463,938	10/15/2002	Wafer Cleaning System
US	08/660,113	6 /7 /1996	5,882,598	3 /16/1999	Wafer Gap Conductivity Cell for Characterizing Process Vessels and Semiconductor Fabrication Processes and Method of Use.
US	09/324,813	6 /2 /1999	6,245,158	6 /12/2001	Wet Processing Methods for the Manufacture of Electronic Components Using Liquids of Varying Temperature
US	08/684,543	7 /19/1996	6,132,522	10/17/2000	Wet Processing Method for the Manufacture of Electronic Components Using Sequential Chemical Processing

COUNTRY	SERIAL NO	FILED	TITLE
TW	096102102	1 /19/2007	Acoustic Energy System, Method and Apparatus for Processing Flat Articles
JP	US2007/060850	1 /22/2007	Acoustic Energy System. Method and Apparatus for Processing Flat Articles
KR	US2007/060850	1 /22/2007	Acoustic Energy System. Method and Apparatus for Processing Flat Articles
US	61/034,142	3 /5 /2008	Acoustic Generating Device
WO	US2003/018384	6 /9 /2003	Apparatus and Method for Cassette-Less Transfer of Wafers
US	11/755,619	5 /30/2007	Apparatus and Method for Cleaning and Drying a Hydrophobic Surface of a Substrate
WO	US07/069983	5 /30/2007	Apparatus and Method for Cleaning and Drying a Hydrophobic Surface of a Substrate
JP	2007-539373	11/3 /2005	Apparatus and Method for Removing Trace Amounts of Liquid From Substrates During Single-Substrate Processing
US	11/266,402	11/3 /2005	Apparatus and Method for Removing Trace Amounts of Liquid From Subtrates During Single-Substrate Processing

COUNTRY	SERIAL NO	FILED	TITLE
TW	096102103	1 /19/2007	Apparatus and Method for Transmitting Energy Through a Non-Reactive Transmitter Bonded to a Transducer and Use of the Smae to Process Substrates
US	11/625,651	1 /22/2007	Apparatus and Method for Transmitting Energy Through a Non-Reactive Transmitter Bonded to a Transducer and Use of the Smae to Process Substrates
WO	US07/60861	1 /22/2007	Apparatus and Method for Transmitting Energy Through a Non-Reactive Transmitter Bonded to a Transducer and Use of the Same to Process Substrates
US	11/837,292	8 /10/2007	Apparatus and Method of Measuring Acoustical Energy Applied to a Substrate
WO	US2007/075729	8 /10/2007	Apparatus and Method of Measuring Acoustical Energy Applied to a Substrate
EP	02731132.3	3 /15/2002	Apparatus and Methods for Vapor Generation System
KR	10-2003-7012039	3 /15/2002	Apparatus and Methods for Vapor Generation System
JP	2002-574701	3 /15/2002	Apparatus and Methods for Vapor Generation System
US	10/931,441	9 /1 /2004	Apparatus for Carrying Reticles and Method of Using the Same to Process Reticles
WO	US2004/028447	9 /1 /2004	Apparatus for Carrying Reticles and Method of Using the Same to Process Reticles
US	11/781,835	7 /23/2007	Apparatus for Ejecting Fluid Onto a Substrate and System and Method Incorporating the Same
WO	US2007/074133	7 /23/2007	Apparatus for Ejecting Fluid onto a Substrate and System and Method Incorporating the Same
US	11/777,258	7 /12/2007	Apparatus, System and Method for Processing a Substrate that Prohibits Air Flow Containing Contaminants and/or Residues from Depositing on the Substrate
WO	US2007/73403	7 /12/2007	Apparatus, System and Method for Processing a Substrate that Prohibits Air Flow Containing Contaminants and/or Residues from Depositing on the Substrate
US	11/625,556	1 /22/2007	Backside Cleaning of Substrates
EP	03707744.3	2 /5 /2003	Capillary Drying of Substrates
CN	03805652.6	2 /5 /2003	Capillary Drying of Substrates
JP	2003-565662	2 /5 /2003	Capillary Drying of Substrates
SG	200404652-0	2 /5 /2003	Capillary Drying of Substrates
KR	2004-7012117	2 /5 /2003	Capillary Drying of Substrates
EP	05818673.5	11/3 /2005	Capillary Drying of Substrates for Single-Substrate Processing
CN	200580037823.0	11/3 /2005	Capillary Drying of Substrates for Single-Substrate Processing
KR	10-2007-7012549	11/3 /2005	Capillary Drying of Substrates for Single-Substrate Processing
JP	4/302551		Chemical Processing System for Maintaining Concentration of Semiconductor Processing Solution
US	10/865,440	6 /10/2004	Megasonic Cleaner and Dryer

COUNTRY	SERIAL NO	FILED	TITLE
US	10/171,431	6 /12/2002	Megasonic Cleaner and Dryer System
US	10/171,494	6 /12/2002	Megasonic Cleaner and Dryer System
KR	10-2003-7016342	6 /12/2002	Megasonic Cleaner and Dryer System
WO	US2002/18762	6 /12/2002	Megasonic Cleaner and Dryer System
WO	US2002/18764	6 /12/2002	Megasonic Cleaner and Dryer System
WO	US2002/18765	6 /12/2002	Megasonic Cleaner and Dryer System
US	10/931,457	9 /1 /2004	Megasonic Cleaner Probe System with Gasified Fluid
WO	US02/22675	7 /16/2002	Megasonic Cleaner Probe System with Gasified Fluid
US	11/489,059	7 /18/2006	Megasonic Cleaning System with Buffered Cavitation Method
EP	04776442.8	6 /10/2004	Megasonic Cleaning Using Supersaturated Cleaning Solution
TW	93116958	6 /11/2004	Megasonic Cleaning Using Supersaturated Cleaning Solution
CN	200480020523.7	6 /10/2004	Megasonic Cleaning Using Supersaturated Cleaning Solution
KR	2005-7023902	6 /10/2004	Megasonic Cleaning Using Supersaturated Cleaning Solution
JP	2006-533684	6 /10/2004	Megasonic Cleaning Using Supersaturated Cleaning Solution
US	11/595,029	11/9 /2006	Megasonic Cleaning Using Supersaturated Solution
EP	03703722.3	1 /7 /2003	Megasonic Probe Energy Director
CN	03805097.8	1 /7 /2003	Megasonic Probe Energy Director
JP	2003-563743	1 /7 /2003	Megasonic Probe Energy Director
SG	200404177-8	1 /7 /2003	Megasonic Probe Energy Director
KR	2004-7011627	1 /7 /2003	Megasonic Probe Energy Director
WO	US2005/031349	9 /1 /2005	Megasonic Processing System with Gasified Fluid
EP	2764002.8	4 /8 /2002	Megazone System
JP	2002-579135	4 /8 /2002	Megazone System
KR	2003-7013102	4 /8 /2002	Megazone System
WO	US02/11248	4 /8 /2002	Megazone System
EP	02762026.9	4 /8 /2002	Membrane Dryer
JP	2002-581076	4 /8 /2002	Membrane Dryer
KR	2003-7013091	4 /8 /2002	Membrane Dryer
US	11/177,147	7 /8 /2005	Method and Apparatus for Creating Ozonated Process Solutions having High Ozone Concentration
WO	US05/024509	7 /8 /2005	Method and Apparatus for Creating Ozonated Process Solutions having High Ozone Concentration
US	11/370,361	3 /8 /2006	Method and System for Cleaning Substrates with Sonic Energy that Reduces or Eliminates Damage to Semiconductor Devices
US	60/985,947	11/6 /2007	Method and System for Processing a Substrate Using a Composite Transmitter
TW	095107855	3 /8 /2006	Method and System for Processing Substrates with Sonic Energy that Reduces or Eliminates Damage to Semiconductor Devices

COUNTRY	SERIAL NO	FILED	TITLE
US	11/370,707	3 /8 /2006	Method and System for Processing Substrates with Sonic Energy that Reduces or Eliminates Damage to Semiconductor Devices
WO	US2006/008452	3 /8 /2006	Method and System for Processing Substrates with Sonic Energy that Reduces or Eliminates Damage to Semiconductor Devices
US	61/031,845	2 /27/2008	Method for Cavitation Measurement
US	12/070,620	2 /19/2008	Method for Post-CMP Advanced Front End of Line Cleaning
US	11/873,750	10/17/2007	Method of Cleaning Substrates Utilizing Megasonic Energy
US	10/537,996	6 /3 /2005	Method of Drying Substrates
TW	096126671	7 /20/2007	Nozzle for Use in the Megasonic Cleaning of Substrates
US	10/053,371	1 /18/2002	Process and Apparatus for Removal of Photoresist from Semiconductor Wafers
WO	US2003/01668	1 /20/2003	Process and Apparatus for Removal of Photoresist from Semiconductor Wafers
WO	US2003/001588	1 /16/2003	Process and Apparatus for Removing Photoresist Using Sparger
JP	5-101531	5 /18/1993	Process for Etching Oxide Films
EP	04779750.1	8 /2 /2004	Process Sequence for Photoresist Stripping and Cleaning of Photomasks for Integrated Circuit Manufacturing
TW	093123002	7 /30/2004	Process Sequence for Photoresist Stripping and Cleaning of Photomasks for Integrated Circuit Manufacturing
US	11/649,535	1 /4 /2007	Process Sequence for Photoresist Stripping and Cleaning of Photomasks for Integrated Circuit Manufacturing
US	11/640,718	12/18/2006	Reciprocating Megasonic Probe
US	11/178,923	7 /11/2005	Reduced Pressure Irradiation Processing Method And Apparatus
EP	05770069.2	7 /8 /2005	Reduced Pressure UV172 Irradiation Chamber
JP	2007-520585	7 /8 /2005	Reduced Pressure UV172 Irradiation Chamber
TW	093126709	9 /3 /2004	Reticle Cleaning Carrier
US	08/140,290	10/20/1993	Semiconductor Wafer Cleaning System
US	08/899,732	7 /24/1997	Semiconductor Wafer Cleaning System
US	07/702,587	5 /17/1991	Semiconductor Wafer Vessel and Apparatus
US	08/195,400	2 /14/1994	Single Wafer Megasonic Semiconductor Wafer Processing System
JP	266441/1991	10/15/1991	Single Wafer Megasonic Semiconductor Wafer Processing System
US	09/916,357	7 /27/2001	Small Parts Cleaner
TW	096116332	5 /8 /2007	Spray Jet Cleaning Apparatus and Method
US	11/745,866	5 /8 /2007	Spray Jet Cleaning Apparatus and Method
WO	US07/068478	5 /8 /2007	Spray Jet Cleaning Apparatus and Method
EP	03778012.9	10/31/2003	Substrate Process Tank with Acoustical Source Transmission and Method of Processing Substrates
CN	200380107761.7	10/31/2003	Substrate Process Tank with Acoustical Source Transmission and Method of Processing Substrates

COUNTRY	SERIAL NO	FILED	TITLE
KR	10-2005-7007603	10/31/2003	Substrate Process Tank with Acoustical Source Transmission and Method of Processing Substrates
TW	096101976	1 /18/2007	System and Method for Drying a Rotating Substrate
US	11/624,445	1 /18/2007	System and Method for Drying a Rotating Substrate
WO	US2007/060709	1 /18/2007	System and Method for Drying a Rotating Substrate
TW	096130582	8 /17/2007	System and Method for Processing a Substrate Utilizing a Gas Stream for Particle Removal
US	11/841,427	8 /20/2007	System and Method for Processing a Substrate Utilizing a Gas Stream for Particle Removal
WO	US2007/076324	8 /20/2007	System and Method for Processing a Substrate Utilizing a Gas Stream for Particle Removal
EP	04815878.6	12/30/2004	System and Method for Selective Etching of Silicon Nitride During Substrate Processing
US	10/585,229	4 /20/2007	System and Method for Selective Etching of Silicon Nitride During Substrate Processing
KR	10-2006-7015378	12/30/2004	System and Method for Selective Etching of Silicon Nitride During Substrate Processing
JP	2006-547553	12/30/2004	System and Method for Selective Etching of Silicon Nitride During Substrate Processing
CN	US04/043887	12/30/2004	System and Method for Selective Etching of Silicon Nitride During Substrate Processing
WO	US2007/081648	10/17/2007	System and Method for Sonic-Assisted Cleaning of Substrates Using Pre-Cavitated Liquid
US	11/176,406	7 /7 /2005	System and Method of Cleaning Semiconductor Substrates Using Ozonoted DI Water
US	11/544,802	10/6 /2006	System and Method of Cleaning Substrates Using a Subambient Process Solution
US	12/059,602	3 /31/2008	System and method of Determining the Operating Frequency at Which to Power a Transducer
EP	05810413.4	9 /15/2005	System and Method of Powering a Sonic Energy Source and Use of the Same to Process Substrates
CN	200580030943.8	9 /15/2005	System and Method of Powering a Sonic Energy Source and Use of the Same to Process Substrates
KR	10-2007-7008639	9 /15/2005	System and Method of Powering a Sonic Energy Source and Use of the Same to Process Substrates
JP	2007-532473	9 /15/2005	System and Method of Powering a Sonic Energy Source and Use of the Same to Process Substrates
WO	US2006/023270	6 /15/2006	System and Method of Processing Substrate Using Sonic Energy Having Cavitation Control
TW	095121451	6 /15/2006	System and Method of Processing Substrates Using Energy Having Cavitation Control
US	11/454,447	6 /15/2006	System and Method of Processing Substrates Using Sonic Energy Having Cavitation Control
TW	094131851	9 /15/2005	System and Method of Supplying power to a Sonic Source and use of the Same to Process Substrates
US	11/227,705	9 /15/2005	System and Method of Supplying power to a Sonic Source and use of the Same to Process Substrates
US	11/839,885	8 /16/2007	System For Megasonic Processing Of An Article
US	09/837,013	4 /18/2001	Thermal Capillary Drying
US	11/777,252	7 /12/2007	Transducer Assembly Incorporating a Transmitter Having Through Holes, and Method and System for Cleaning a Substrate Utilizing the Same

COUNTRY	SERIAL NO	FILED	TITLE
WO	US2007/073402	7 /12/2007	Transducer Assembly Incorporating a Transmitter Having through Holes, And Method and System for cleaning a substrate utilizing the Same
MY	PI 99004236	9 /30/1999	Vapor Drying System and Method

Exhibit B
"Trademarks"

COUNTRY	MARK	APP NO	FILED	REG NO	REG DATE
CA	AKRION	1,156,020	10/17/2002	608,876	4 /29/2004
SG	AKRION	T99/015161	2 /18/1999	S/1516/99	8 /16/2000
KR	AKRION	1999-4850	2 /18/1999	476864	9 /14/2000
MY	AKRION	1323/99	2 /19/1999	1999-01323	2 /19/1999
KR	AKRION	2002-47885	10/18/2002	566614	11/26/2003
JP	AKRION	11-12076	2 /16/1999	4404040	7 /28/2000
TW	AKRION	88007505	2 /24/1999	00922154	1 /1 /2001
TW	AKRION	91043585	10/17/2002	1085189	2 /16/2004
US	AKRION	78/122,937	4 /19/2002	2,691,082	2 /25/2003
EU	AKRION	2894970	10/17/2002	2894970	12/12/2003
SG	AKRION	T02/16311D	10/18/2002	T02/16311D	9 /6 /2003
JP	AKRION	87963/2002	10/17/2000	4688464	7 /4 /2003
TW	AKRION (in chinese characters)	092032404	5 /20/2003	1098920	5 /1 /2004
JP	GOLDFINGER	021874/1999	3 /10/1999	4519693	11/2 /2001
US	GOLDFINGER	75/555,468	9 /18/1998	2,295,797	11/30/1999
KP	GOLDFINGER	99-8294	3 /17/1999	468120	4 /14/2000
EU	GOLDFINGER	1100908	3 /10/1999		
TW	LUCID2	92054564	9 /12/2003	1115142	8 /16/2004
US	LUCID2	78/224,085	3 /11/2003	2,993,100	9 /6 /2005
SG	LUCID2	T03/14557H	9 /11/2003	T03/14557H	2 /15/2005
JP	LUCID2	79019/2003	9 /11/2003	4749321	2 /20/2004
CN	LUCID2	3715221	9 /12/2003	3715221	10/28/2005
US	SUBMICRON	73/817,473	8 /7 /1989	1,598,327	5 /29/1990
US	SUNBURST	73/760,371	10/28/1988	1,574,491	1 /2 /1990
US	V & Design	76/274,785	6 /21/2001	2,604,390	8 /6 /2002
US	V VERTEQ & Design	76/274,881	6 /21/2001	2,655,977	12/3 /2002
US	VERTEQ	75/035,442	12/21/1995	2,040,148	2 /25/1997